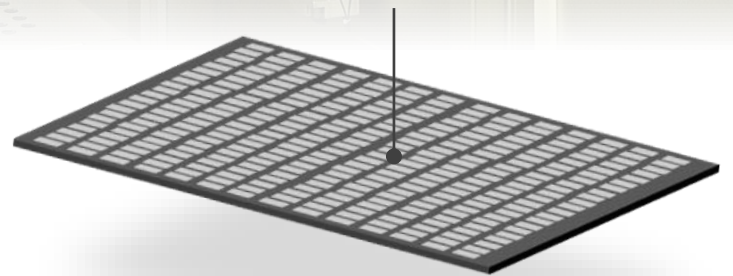




600mm Large Square Panel
Fan-out WLP solution



Fan-out Panel Level Packaging Solution

nPLP™ for High-Tech Semiconductor

Flexible productivity



5X Production efficiency
than 300mm FOWLP

Cost Effectiveness



30% Cost reduction

High Reliability



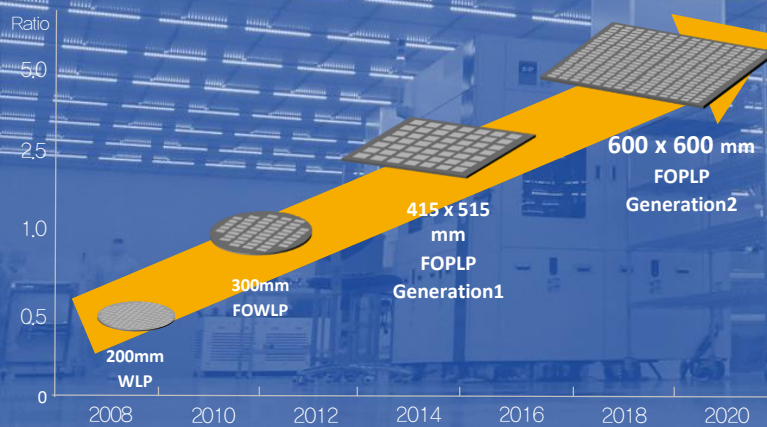
Better Chip PKG Interaction
Higher Board Level Reliability

What is nPLP™?

- The largest panel size which leads to the new standard panel size
- PLP has a technology superiority as the same level of Fan-out package, while it has a price competitive edge against classic types of package



nPLP™ is Leading Advanced Packaging Technology



FOWLP

nPLP™

- ▶ **5X** production efficiency in the same process of FOWLP
- ▶ **30%** Cost reduction

nepes' Technology changes global supply chain

nepes Fan-out package technology, Large panel know-how & Internal materials development



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